

SOT2055-1

FBGA1150, fine pitch ball grid array package, 1150 terminals,
0.65 mm pitch, 23 mm x 23 mm x 2.07 mm body

2 March 2021

Package information

1 Package summary

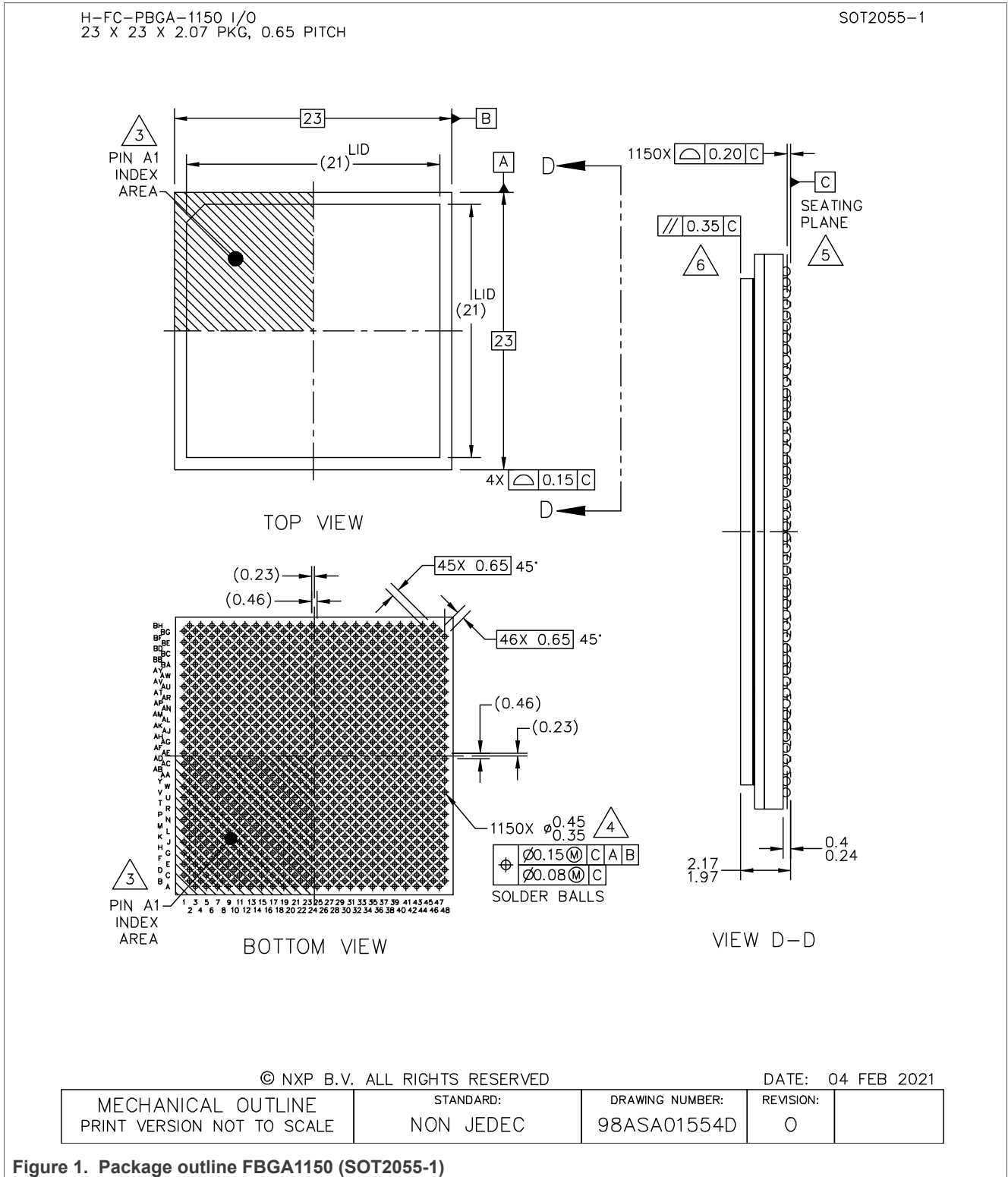
Terminal position code	B (bottom)
Package type descriptive code	FBGA1150
Package style descriptive code	FBGA (fine-pitch ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	04-02-2021
Manufacturer package code	98ASA01554D

Table 1. Package summary

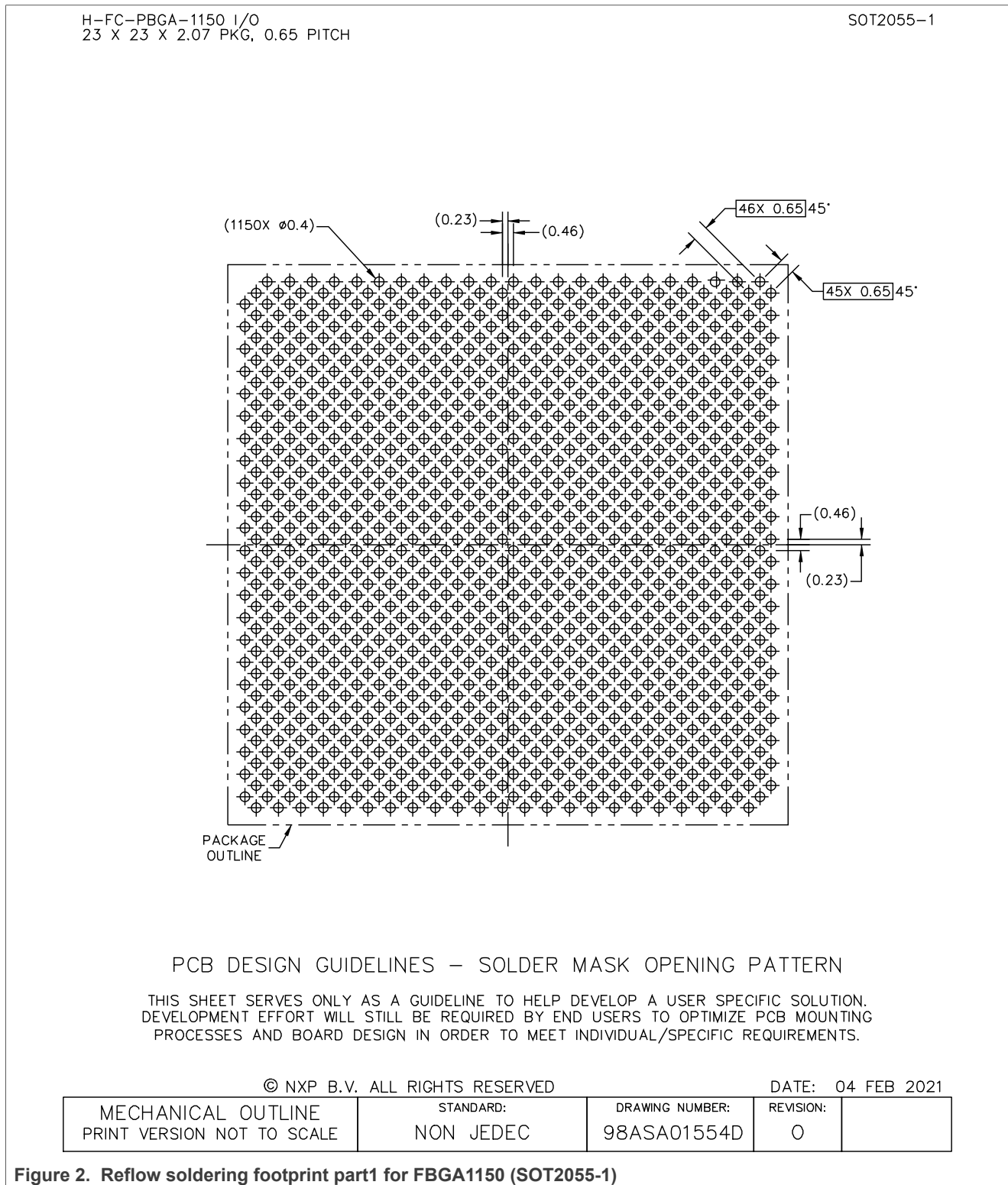
Parameter	Min	Nom	Max	Unit
package length	22.85	23	23.15	mm
package width	22.85	23	23.15	mm
package height	1.97	2.07	2.17	mm
nominal pitch	-	0.65	-	mm
actual quantity of termination	-	1150	-	

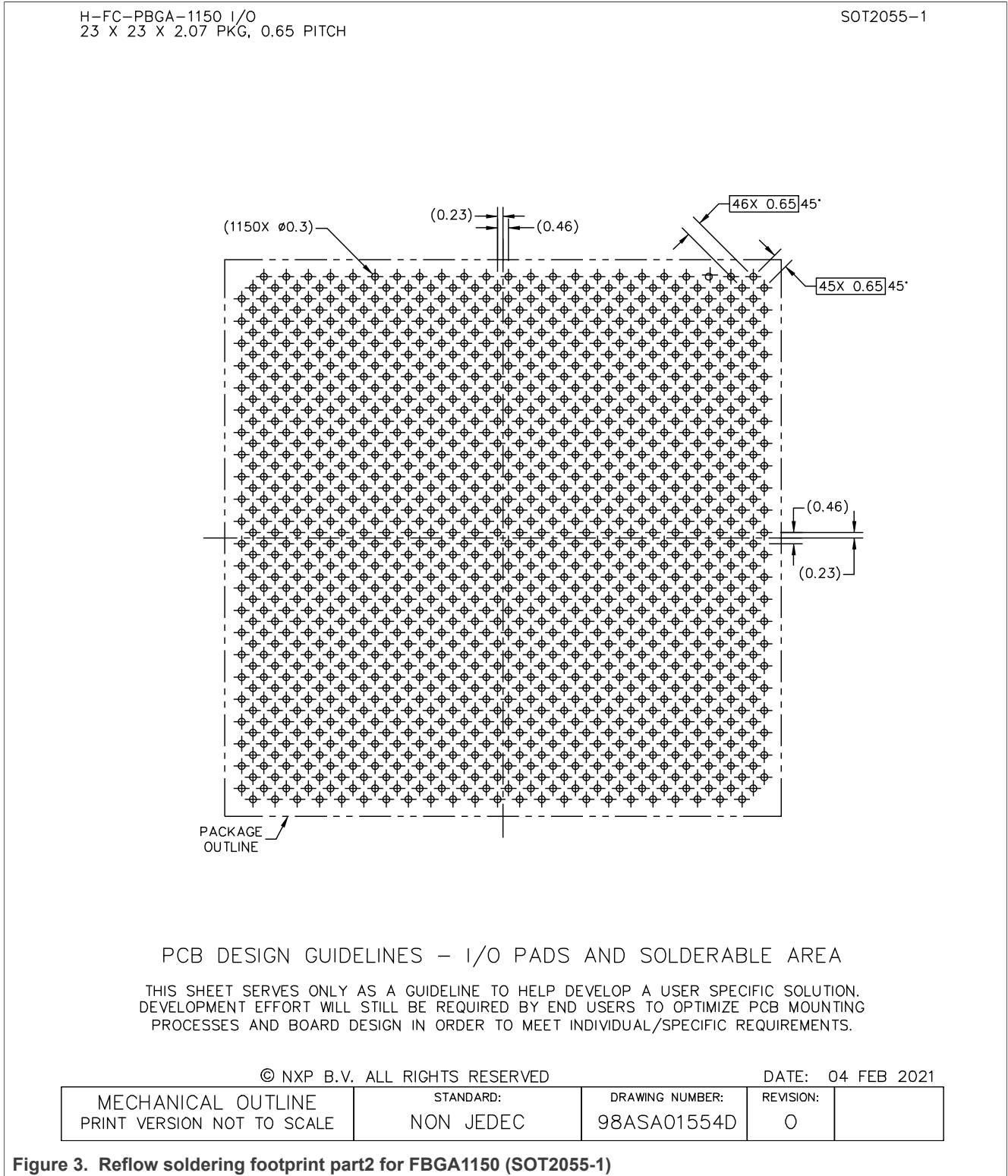


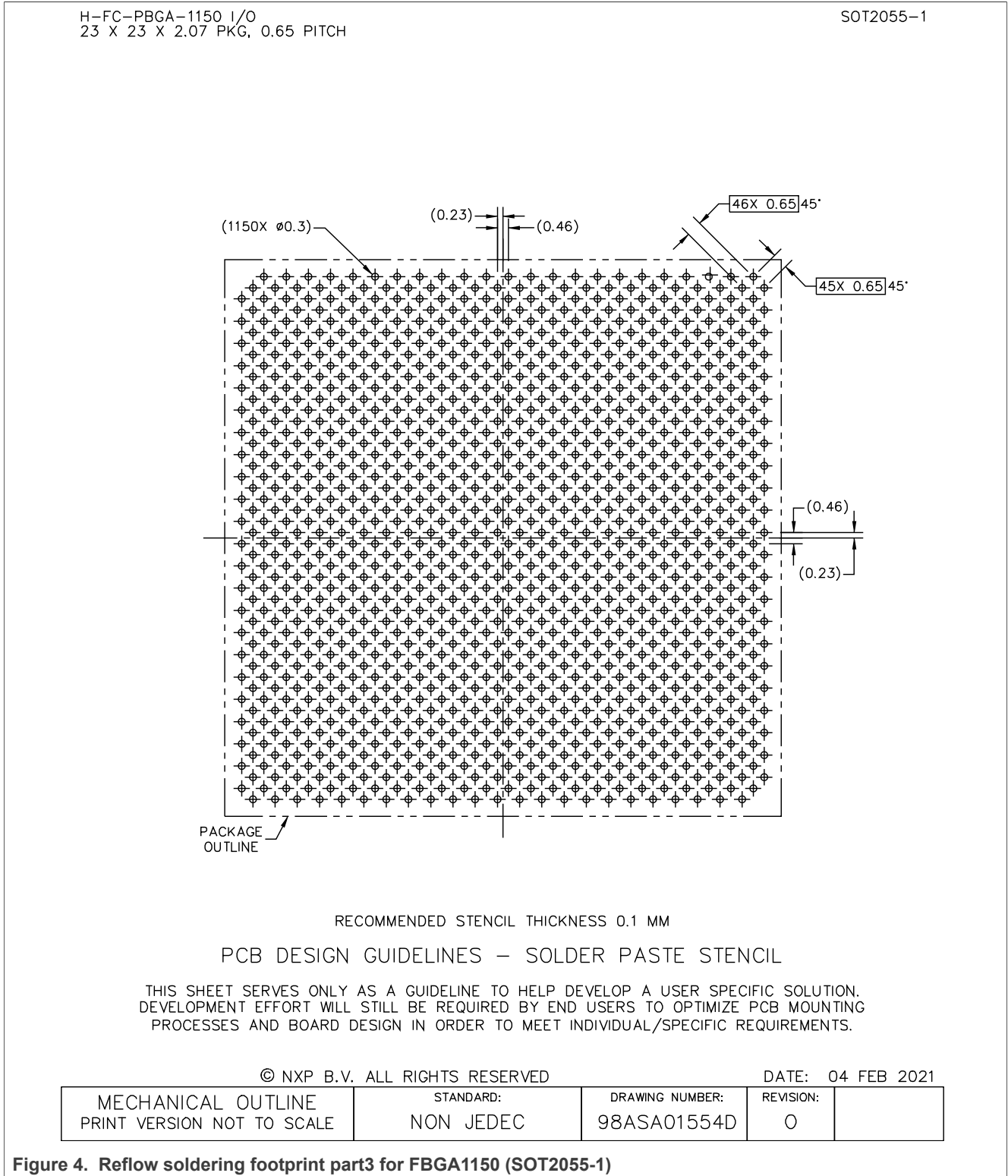
2 Package outline



3 Soldering







FBGA1150, fine pitch ball grid array package, 1150 terminals, 0.65 mm pitch, 23 mm x 23 mm x 2.07 mm body

H-FC-PBGA-1150 I/O
23 X 23 X 2.07 PKG, 0.65 PITCH

SOT2055-1

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.
7. LID OVERHANG ON SUBSTRATE NOT ALLOWED.

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DATE: 04 FEB 2021

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01554D	REVISION: 0	
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Figure 5. Package outline note FBGA1150 (SOT2055-1)

4 Legal information

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